

RELIABILITY REPORT  
FOR  
MAX248CQH+D  
PLASTIC ENCAPSULATED DEVICES

April 15, 2011

**MAXIM INTEGRATED PRODUCTS**

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<b>Approved by</b>
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Quality Assurance
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## Conclusion

The MAX248CQH+D successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX220-MAX249 family of line drivers/receivers is intended for all EIA/TIA-232E and V.28/V.24 communications interfaces, particularly applications where  $\pm 12V$  is not available. These parts are especially useful in battery-powered systems, since their low-power shutdown mode reduces power dissipation to less than  $5\mu W$ . The MAX225, MAX233, MAX235, and MAX245/MAX246/MAX247 use no external components and are recommended for applications where printed circuit board space is critical.

## II. Manufacturing Information

A. Description/Function:	+5V-Powered, Multichannel RS-232 Drivers/Receivers
B. Process:	SG5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines
F. Date of Initial Production:	Pre 1997

## III. Packaging Information

A. Package Type:	44-pin PLCC
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0701-0481
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 3
J. Single Layer Theta Ja:	75°C/W
K. Single Layer Theta Jc:	21°C/W
L. Multi Layer Theta Ja:	N/A°C/W
M. Multi Layer Theta Jc:	N/A°C/W

## IV. Die Information

A. Dimensions:	156 X 178 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)  
Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{1000 \times 4340 \times 231 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 0.9 \times 10^{-9}$$

$$\lambda = 0.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the SG5 Process results in a FIT Rate of 0.12 @ 25C and 2.04 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing (lot NEXDFA012A D/C 9952)

The PS24-3 die type has been found to have all pins able to withstand a HBM transient pulse of +/-800V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX248CQH+D**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C	DC Parameters	77	0	NEXDFA080C, D/C 0208
	Biased	& functionality	77	0	NEXDFA080B, D/C 0208
	Time = 1000 hrs.		77	0	NEXDFA080D, D/C 0208

Note 1: Life Test Data may represent plastic DIP qualification lots.